



Your Smart Dispensing Solution Delivering Speed and Accuracy

ACELON™

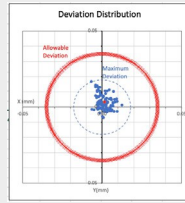
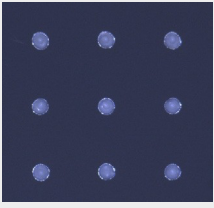
KEY FEATURES

- 01 High Performance Dispenser for Underfill, Solder Paste, Epoxy, Dam & Fill, SMT, LED Encapsulation**
- 02 Built on the Proven K&S Wedge Bonder Platform — Over 3,000 units in Mass Production**
- 03 Expanded Working Area [XYZ]: 360 × 600 × 100 mm**
- 04 Precise Glue Dispensing with Accuracy: < 20 μm**
- 05 Automatic Calibration Functions**
- 06 Optional “Twin Valve, Dual Valve” Configuration Designed to Enhance UPH Performance**
- 07 Optional Tiltable Valve with Programmable Tilt Angle for Precise Dispensing at Various Angles**
- 08 High Repeatability Accuracy to Reduce KOZ to < 180um**
- 09 Intelligent Software for Enhanced Throughput and Quality**
 - Closed Loop Flow Volume Control
 - Real Time Dispensing Height Measurement and Compensation
 - On-the-Fly Alignment Vision System Post-Dispensing Inspection Reduces Defect Rates
 - “Smart Underfill” Software Boosts UPH Performance
 - AI-Based Auto Parameter Tuning (APT)

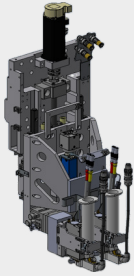
**YOUR ALLY IN
TECHNOLOGICAL
DISCOVERY,
ALWAYS.**

ACELON™

ENHANCED ACCURACY WITH DOT CHARTS



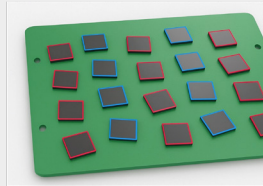
TWIN HEAD/DUAL HEAD TECHNOLOGY



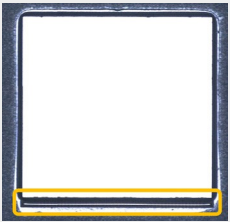
Dual Valve Real-Time Position Compensation

Red and Blue Diagram:
Rotated/ Offset Path

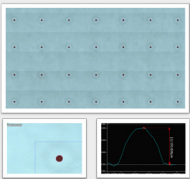
- Valve 1: Red Path
- Valve 2: Blue Path



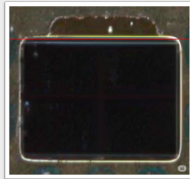
UNDERFILL DISPENSING DESCRIPTION WITH PHOTO



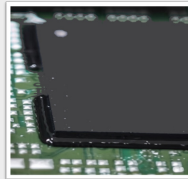
WIDE APPLICATION EXAMPLES WITH DESCRIPTION AND PHOTOS



Dot Dispensing with Flying Dispensing



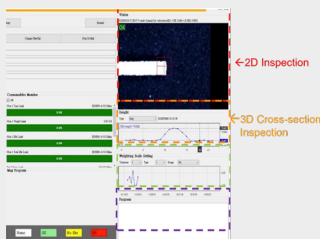
Underfill



Edge Bond

SOFTWARE FEATURES

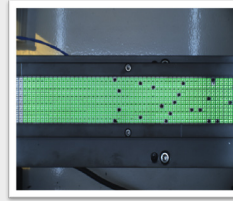
	Conventional Underfill	Smart Underfill
Group	Fixed Group by process engineer	Dynamic Grouping by software
Sequence	Group-by-Group	Auto-Optimized Scheduling
Recipe Change	Fine Tuning by process engineer	Software Re-Optimizing by software
Idle Time Utilization	Clean, Weighting	Dispensing, and Extensible Tasks (Clean, Weighting) Can support post-AOI in the future



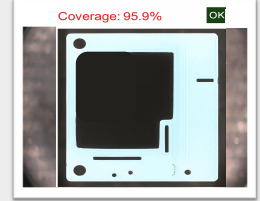
←2D Inspection

←3D Cross-section Inspection

ENHANCES QUALITY WITH POST-DISPENSING INSPECTION TO REDUCE DEFECT RATES



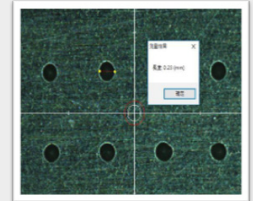
LED Chip Inspection



Glue Coverage



Underfill KOZ Inspection

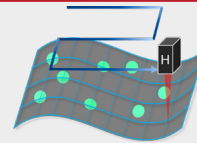


Solder Diameter Measurement

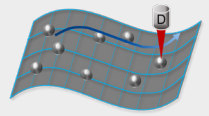
REAL TIME DISPENSING HEIGHT MEASUREMENT AND COMPENSATION

- Real Time Dispensing Height Measurement and Compensation

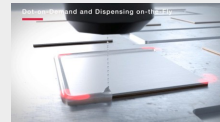
Real-time 3D Graphic Reconstruction On-the-Fly



After Real-Time 3D Process Compensation



- Dot on Demand



SPECIFICATIONS

SPECIFICATION	ACELON	ACELON-LA
Dispensing Area-Single Valve(X/Y mm)	310*400	360*400
Velocity(X/Y/Z mm/s)	310*600(Customize)	360*600(Customize)
Acceleration(X/Y/Z g)	1000/1000/100	
Repeatability (X/Y/Z μm)	1.5/1.5/0.25	
Position Accuracy(X/Y/Z μm)	±3/±3/±3	
XYZ Resolution(μm)	±9/±9/±6	
Height Detector Accuracy	0.1/0.1/0.1	
Weight Scale	5μm	
Available Applicator	Optional 0.1 or 0.01 mg	
Multi Valve Capability	Jet valve, Auger Valve	
Transport	Twin Valve	Dual Valve
Dimension(W/D/H mm)	Standard: Single, Optional: Dual Lane	
Weight(Kg)	788*1776*2202	
Power	1,250kg	
	200~240VAC	
	Single Phase 30A Max,50/60HZ	

For sales, service and manufacturing locations, visit www.kns.com

© 2025 Kulicke & Soffa Industries Inc. Specifications may change without notice. The K&S logo and Kulicke & Soffa are trademarks of Kulicke & Soffa Industries, Inc.

ADS-001-08/2025